

VOLTAGE REGULATOR WITH ON/OFF SWITCH

FEATURES

- Low Dropout Voltage
- CMOS/TTL Compatible ON/OFF Switch
- Very Low Standby Current 180 μ A (ON, No Load)
- Internal Thermal Shutdown
- Short Circuit Protection
- Very Low (0.1 μ A) Current in OFF Mode
- Low Noise with External Bypass Capacitor
- 130 mA Current Capability

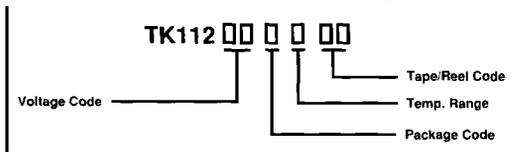
DESCRIPTION

The TK112XX is a low power, linear regulator with a built-in electronic switch. The internal electronic switch can be controlled by TTL or CMOS logic levels. The device is in the ON state when the control pin is pulled to a high logic level. A pin for a bypass capacitor is provided, which connects to the internal circuitry, to lower the overall output noise level.

An internal PNP pass-transistor is used in order to achieve low dropout voltage (typically 100 mV at 30 mA load current). The device has very low quiescent current (180 μ A) in the ON mode with no load and 1 mA with 30 mA load. The quiescent current is typically 2.5 mA at 60 mA load. When the device is in standby mode ($V_{CONT} = 0$), the quiescent current is typically 100 nA. An internal thermal shutdown circuit limits the junction temperature to below 150 $^{\circ}$ C. The load current is internally monitored and the device will shut down in the presence of a short circuit at the output.

Custom versions of the IC are available and the regulated output voltage may be specified in 0.5 V increments between 2.0 to 5.5 V. Additionally, 3.25 V, 6.0 V and 8.0 V versions can be obtained.

ORDERING INFORMATION

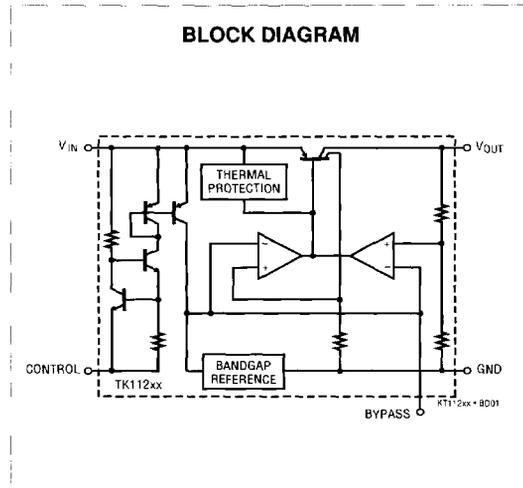
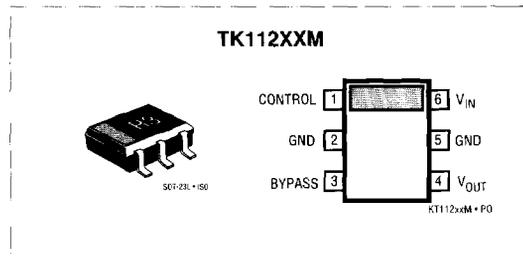


VOLTAGE CODE	PACKAGE CODE	TAPE/REEL CODE
20 = 2.0 V 27 = 2.75 V 40 = 4.0 V	T : Surface Mount	BX : Bulk/Bag
21 = 2.1 V 30 = 3.0 V 45 = 4.5 V		TX : Paper Tape
22 = 2.25 V 32 = 3.25 V 47 = 4.75 V	TEMP. RANGE	TR : Tape Right
25 = 2.5 V 35 = 3.5 V 50 = 5.0 V	I : -40 to +85 $^{\circ}$ C	TL : Tape Left
55 = 5.5 V		MG : Magazine

APPLICATIONS

- Battery Powered Systems
- Cellular Telephones
- Pagers
- Personal Communications Equipment
- Portable Instrumentation
- Portable Consumer Equipment
- Radio Control Systems
- Toys
- Low Voltage Systems

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TK112XX

ABSOLUTE MAXIMUM RATINGS

Supply Voltage	16 V	Storage Temperature Range	-55 to +150 °C
Output Voltage	$V_{OUT} \times 1.15$ V	Operating Temperature Range (Note 2)	-40 to +85 °C
Output Current	220 mA	Lead Soldering Temp. (10 sec.)	240 °C
Power Dissipation (Note 1)	200 mW	Junction Temperature	15 °C

ELECTRICAL CHARACTERISTICS

Test conditions: $T_A = 25$ °C, unless otherwise specified.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{CC1}	Supply Current 1	$I_O = 0$ mA, Except I_{CONT}		180.0		μ A
I_{CC2}	Supply Current 2	$V_{IN} = 8$ V, Output off			100	nA
V_O	Output Voltage	$V_{IN} = V_O + 1$ V, $I_O = 30$ mA	-3	V_O	+3	%
V_O	Output Voltage	$V_{IN} = V_O = 030$ mA	-100	V_O	+100	%
V_{DROP}	In/Out Voltage Drop	$I_O = 30$ mA		0.1		V
I_O	Output Current	Note 3	150	180		mA
I_{OR}	Recommended Output Current				130.0	mA
LinReg	Line Regulation	$V_{IN} = V_O + (1 \sim 6)$			0.12	%/V
LoaReg	Loading Regulation 1	$I_O = 0$ mA ~ 60 mA, Note 4			0.03	%/mA
RR	Ripple Rejection Temperature Coefficient	100 mV(rms), $f = 400$ Hz, $I_O = 10$ mA, $V_O + 1.5$ V		60.0		dB
$\Delta V_O / \Delta T_A$	Temperature Dependency of V_O	$I_O = 10$ mA, $V_O + 1.5$ V $T_A = -25 \sim +75$ °C		0.2		mV/°C
V_{NO}	Output Noise Voltage	10 Hz < f < 80 kHz, $I_O = 10$ mA		30.0		μ V(rms)

Control Terminal Specification

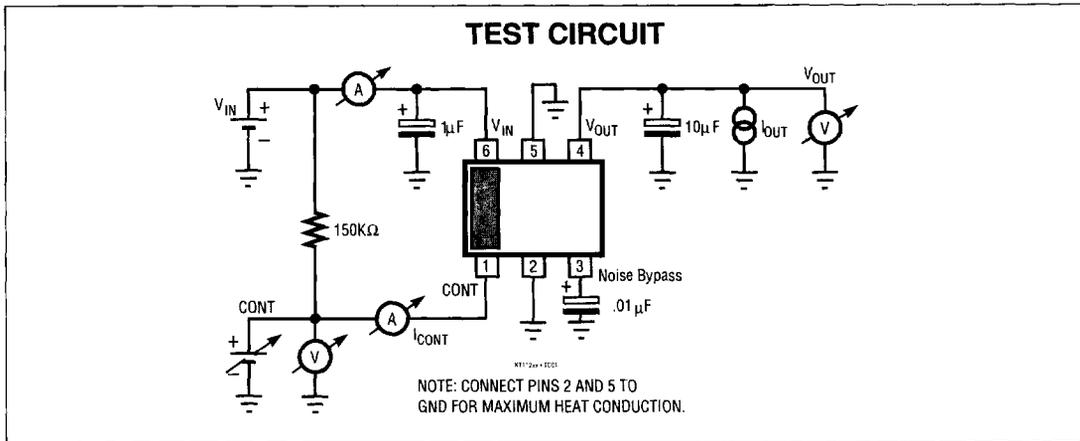
I_{CONT}	Control Terminal Current	Output on, $V_{CONT} = 2.4$ V		15.0	40.0	μ A
V_{CONT1}	Control Terminal Voltage 1	Output on	2.4			V
V_{CONT2}	Control Terminal Voltage 2	Output off			0.6	V
T_R	Output Rise Time	$I_O = 60$ mA, $V_{CONT} = 0$ V ~ 2.4 V		0.2	1.0	ms
	Bypass Terminal Voltage			1.25		V

Note 1: Power dissipation must be derated at rate of 1.6 mW/°C for operation at 25 °C and over. Power dissipation = 400 mW (When mounted as recommended.)

Note 2: Output side capacitor should have low ESR at low temperatures if used below 0 °C.

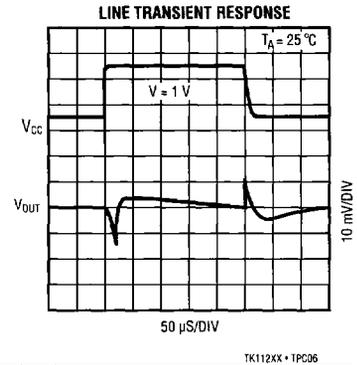
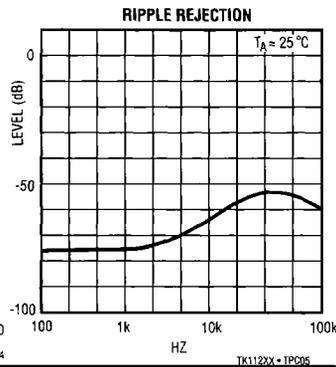
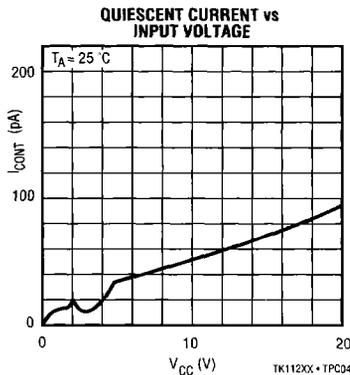
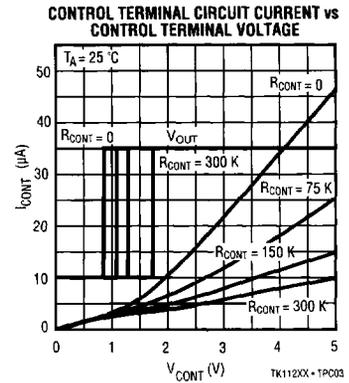
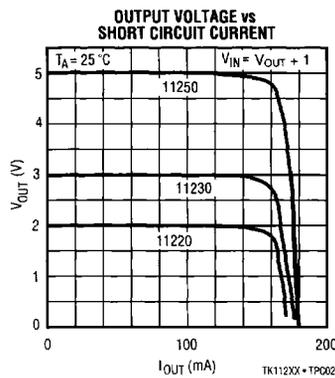
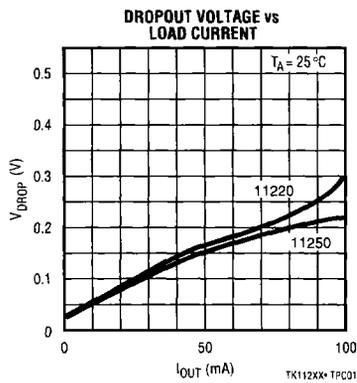
Note 3: I_O (Load Current) is the measured current when V_O drops 0.3 V with respect to (V_O at $I_O = 30$ mA).

Note 4: This measurement (pulse measurement) is with a constant T_J . The output change due to temperature change is not included.

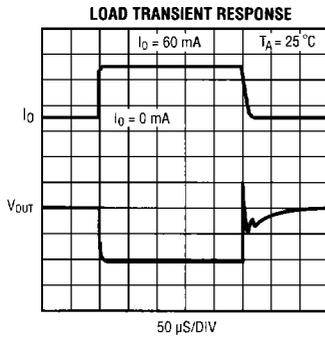


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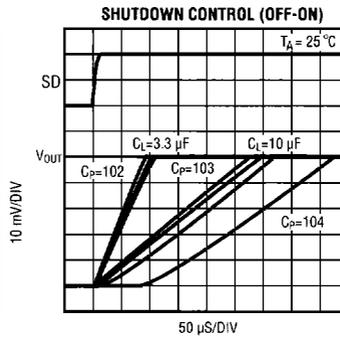
TYPICAL PERFORMANCE CHARACTERISTICS



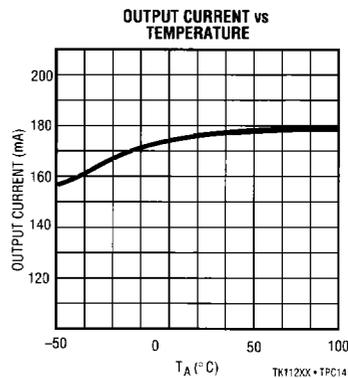
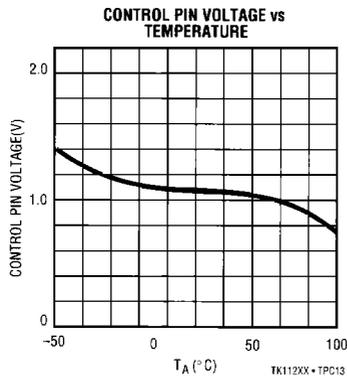
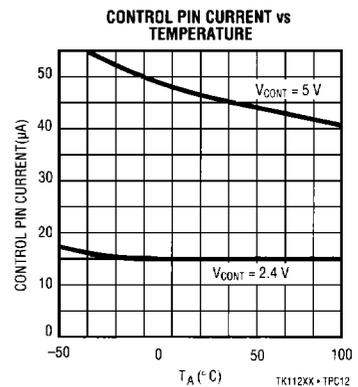
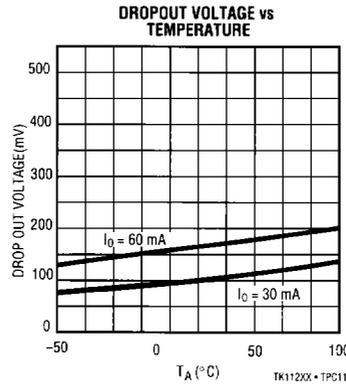
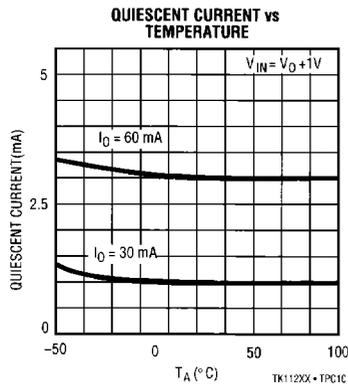
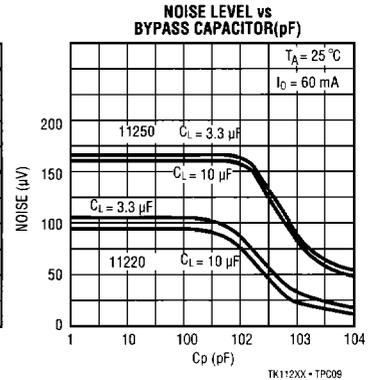
TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)



TK112XX - TPC07

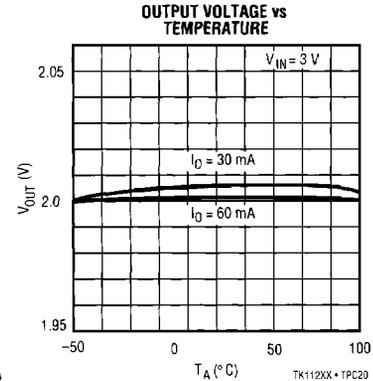
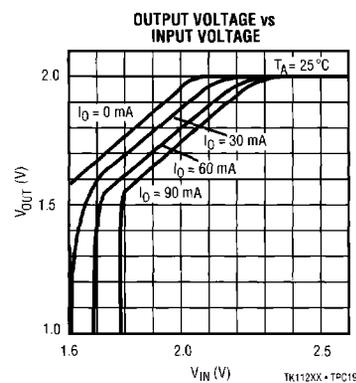
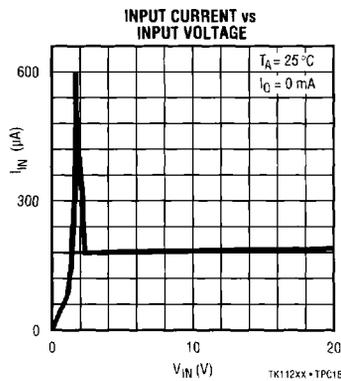
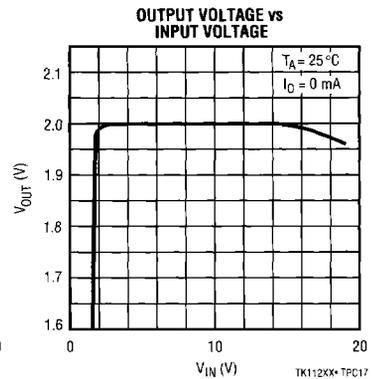
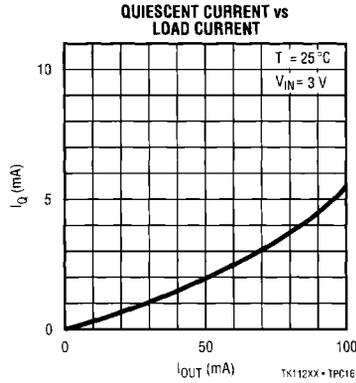
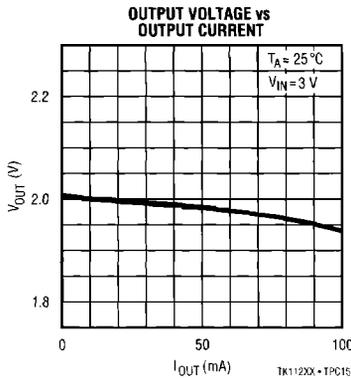


TK1196D - TPC09

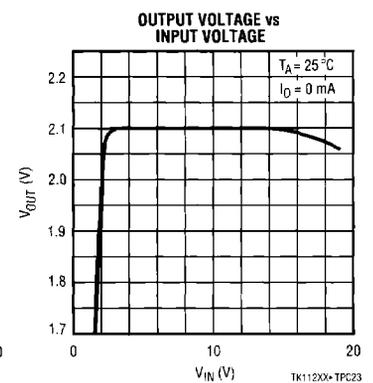
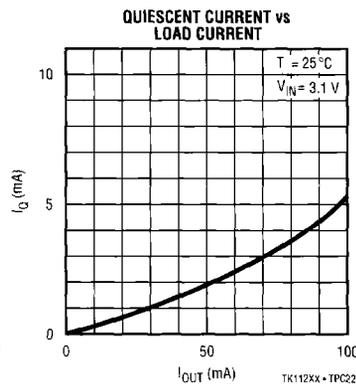
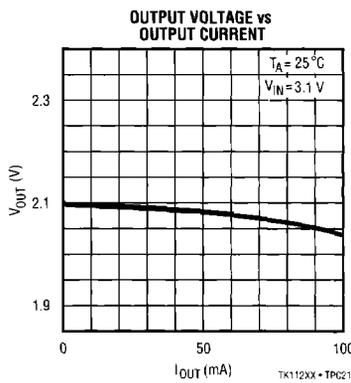


TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11220



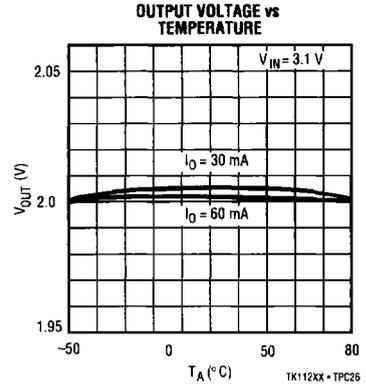
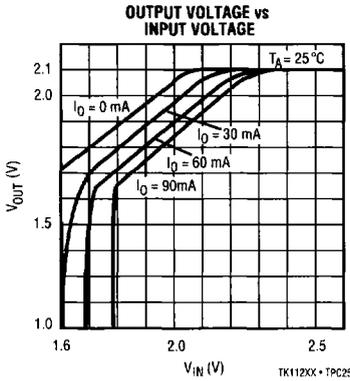
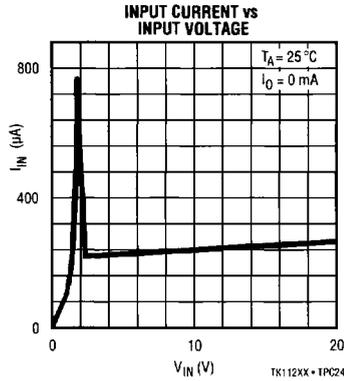
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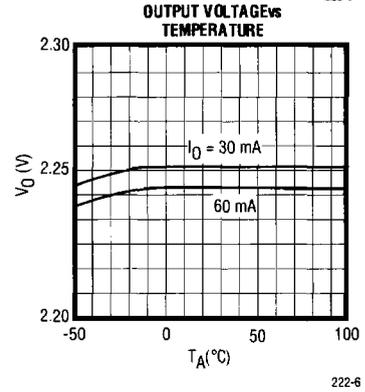
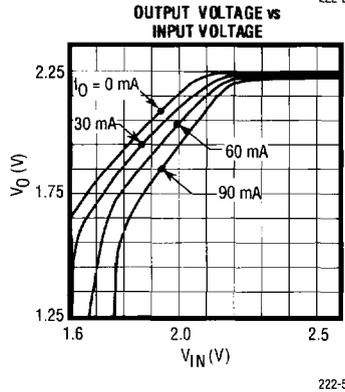
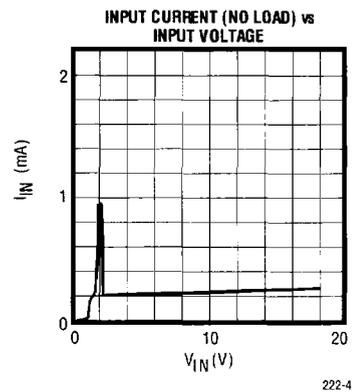
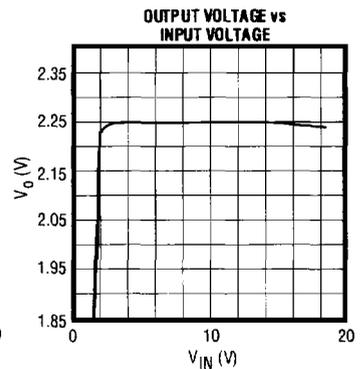
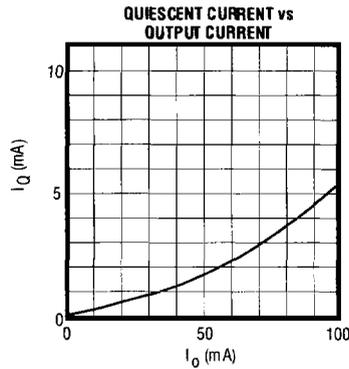
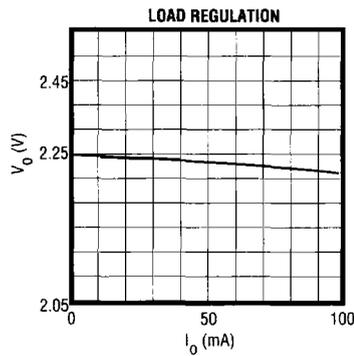
TK112XX

TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11221 (CONT.)



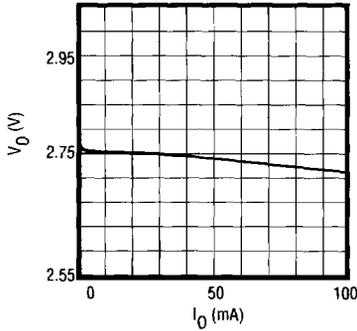
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TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

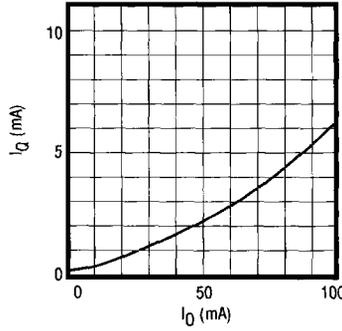
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LOAD REGULATION



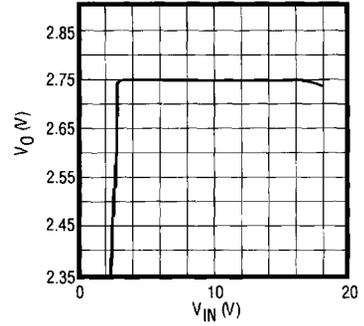
227-1

QUIESCENT CURRENT vs OUTPUT CURRENT



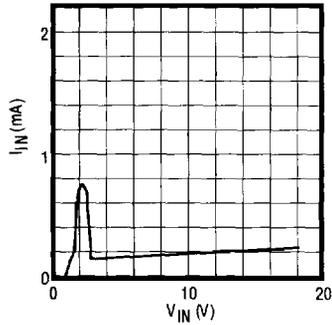
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OUTPUT VOLTAGE vs INPUT VOLTAGE



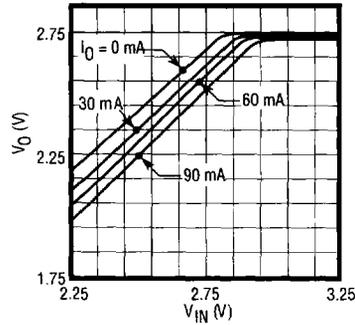
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INPUT CURRENT (NO LOAD) vs INPUT VOLTAGE



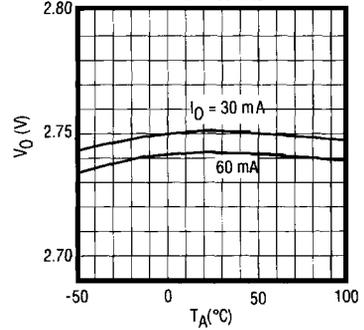
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OUTPUT VOLTAGE vs INPUT VOLTAGE



227-5

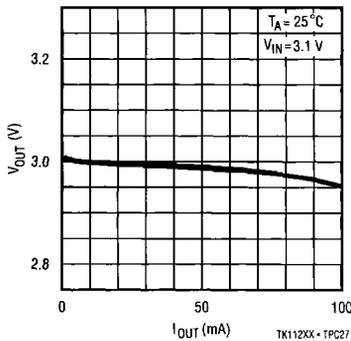
OUTPUT VOLTAGE vs TEMPERATURE



227-6

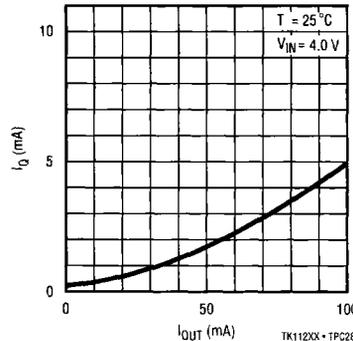
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OUTPUT VOLTAGE vs OUTPUT CURRENT



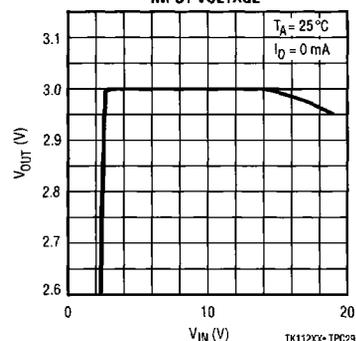
TK112XX-TPC27

QUIESCENT CURRENT vs LOAD CURRENT



TK112XX-TPC28

OUTPUT VOLTAGE vs INPUT VOLTAGE

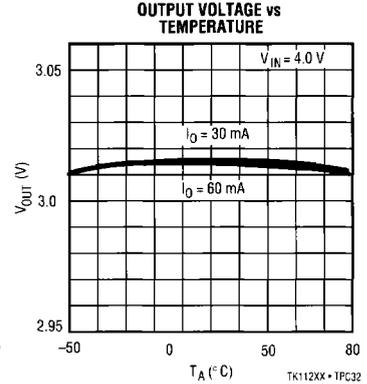
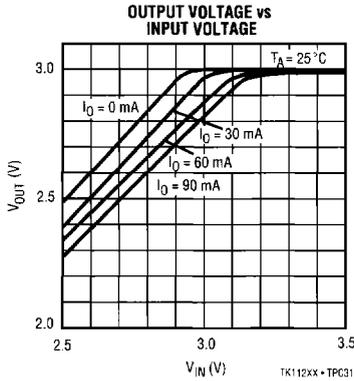
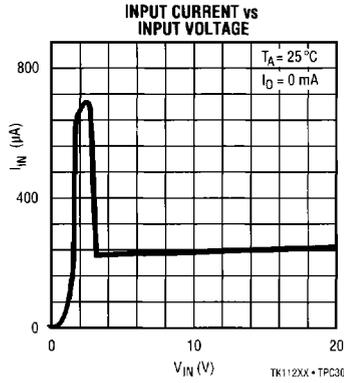


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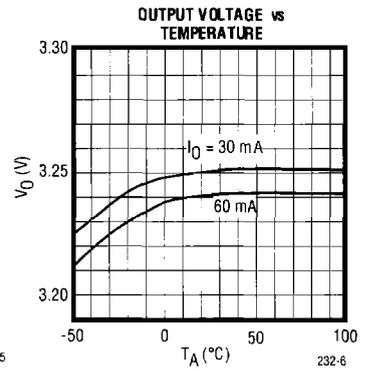
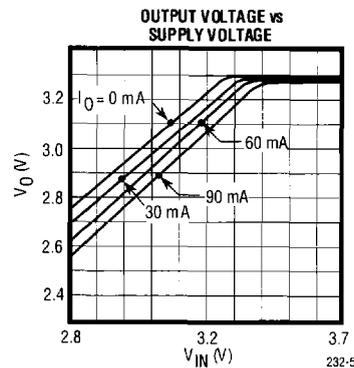
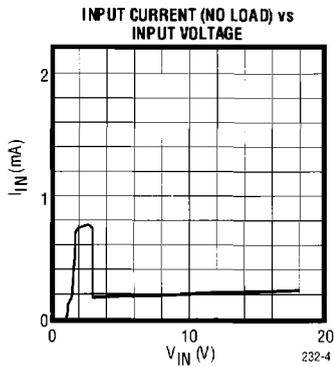
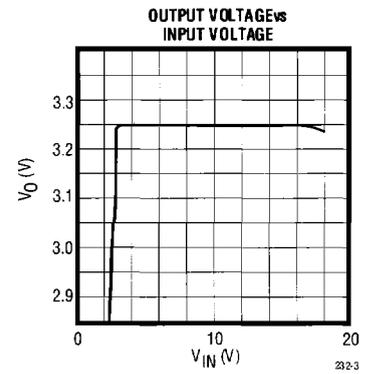
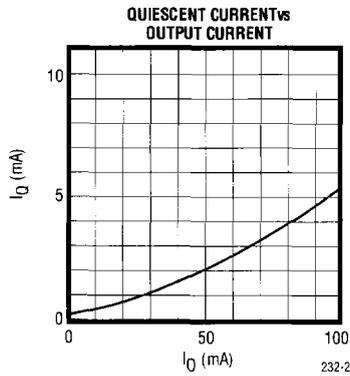
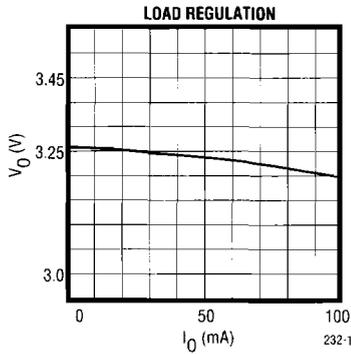
TK112XX

TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11230 (CONT.)

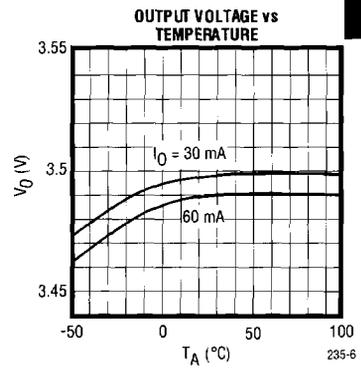
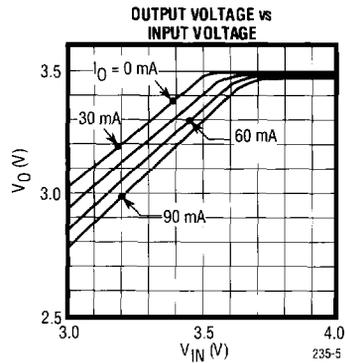
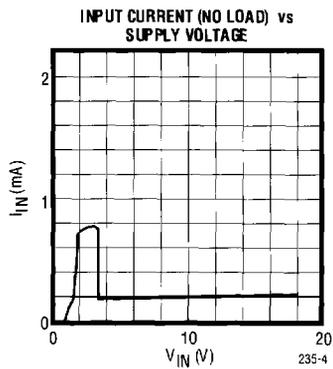
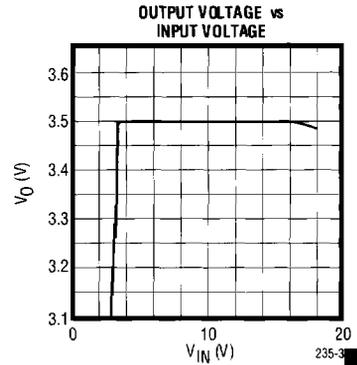
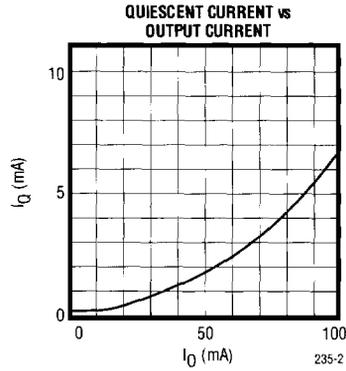
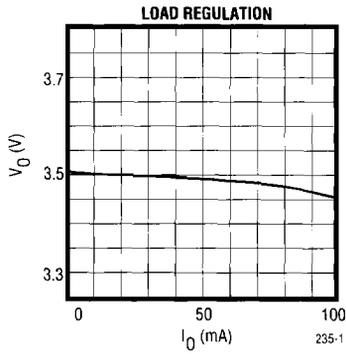


TK11232



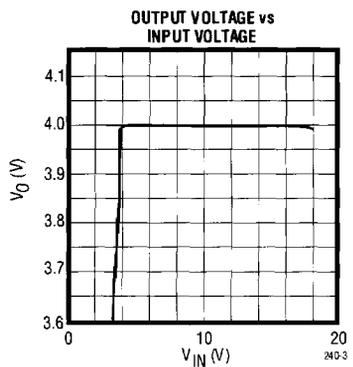
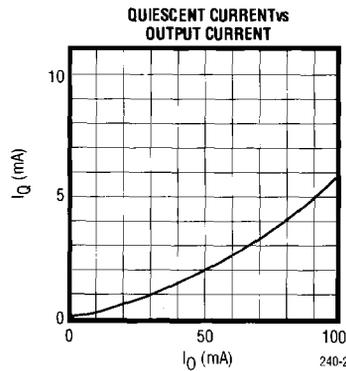
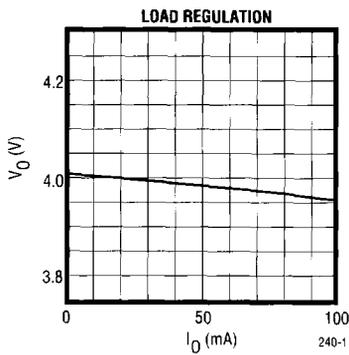
TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11235



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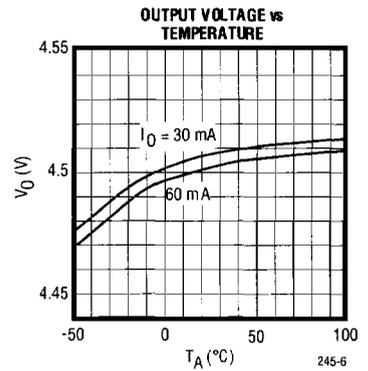
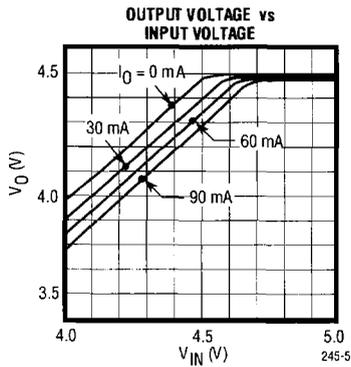
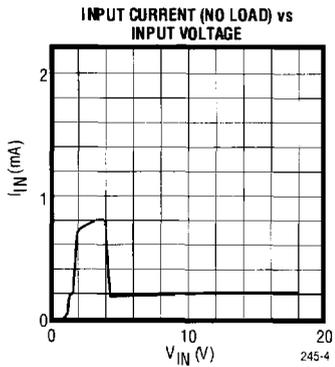
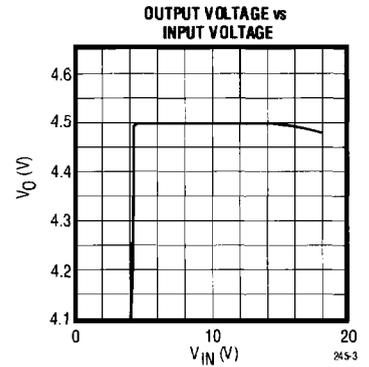
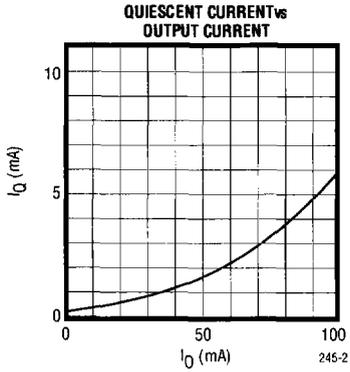
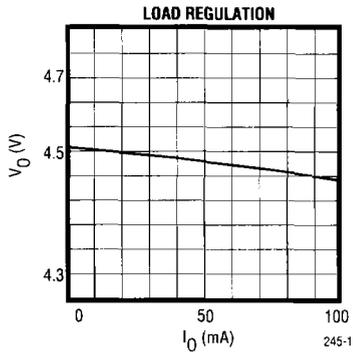
TK11240



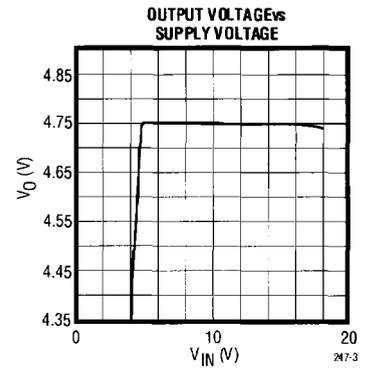
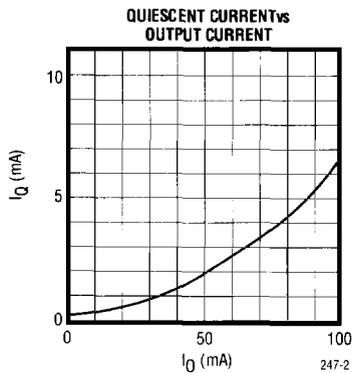
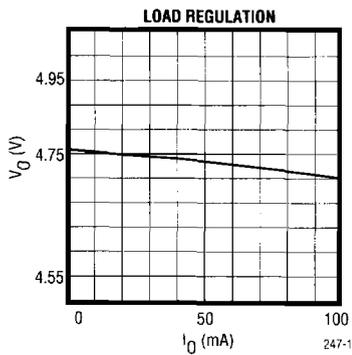
TK112XX

TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11245

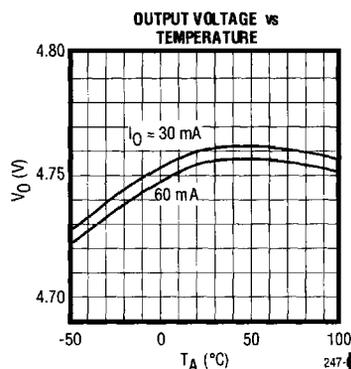
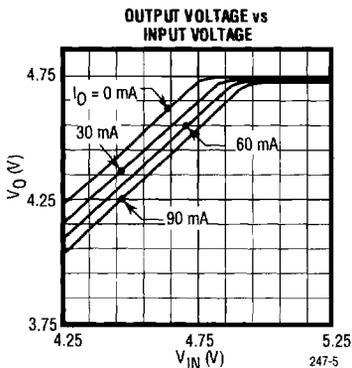
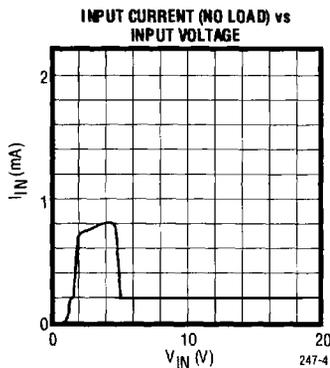


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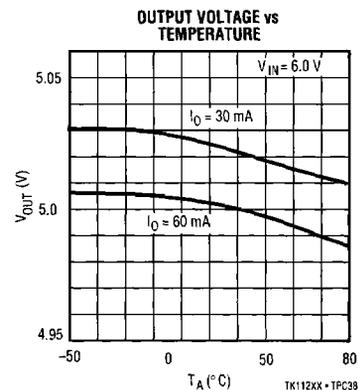
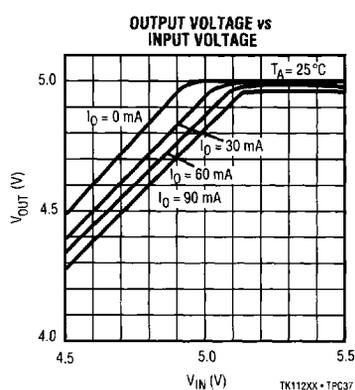
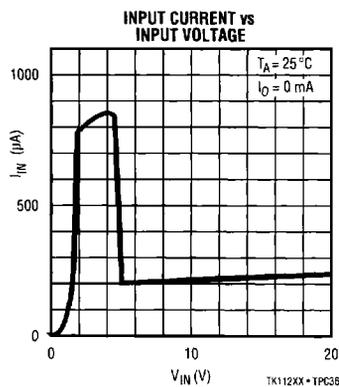
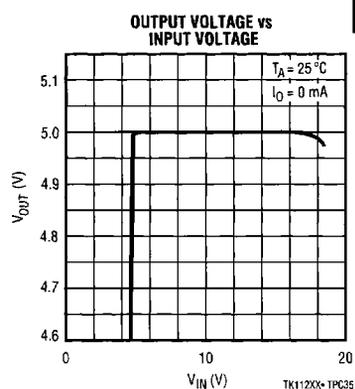
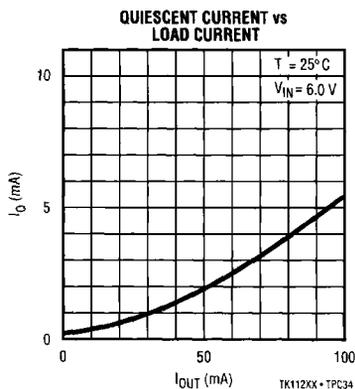
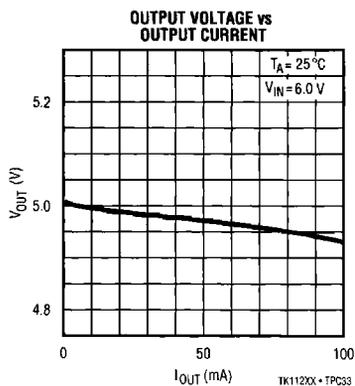


TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11247 (CONT.)

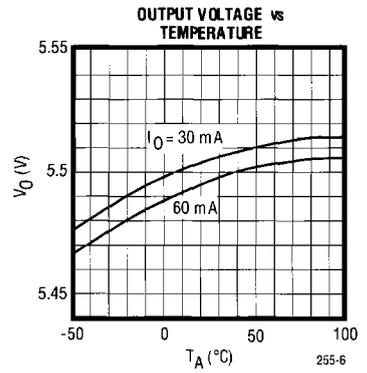
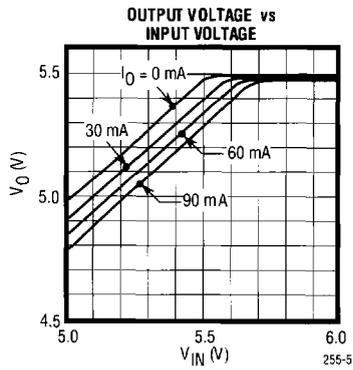
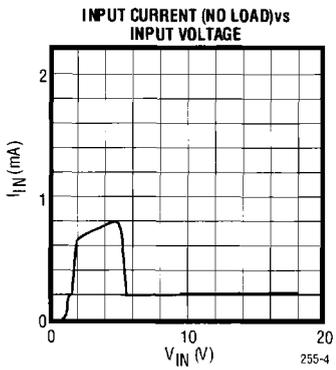
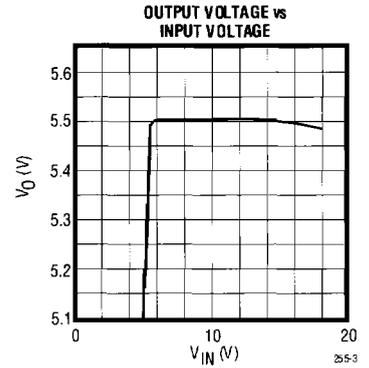
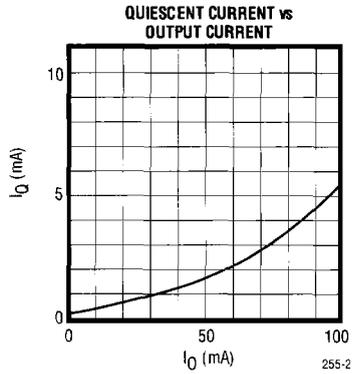
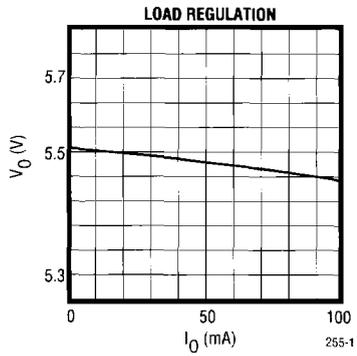


TK11250



TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11255



APPLICATIONS INFORMATION

1.) DISABLING THE CONTROL PIN

Connect control terminal to V_{CC} through R. Higher resistance values are good for reducing quiescent current but can cause the regulator to drop out at a higher voltage. ($0 \Omega < R < 300 \text{ k}\Omega$.) See Figure A.

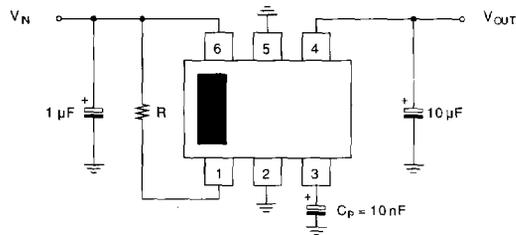


Figure A.

2.) USING THE CONTROL FUNCTION

Turn on the regulator by setting the control pin voltage to the same level as V_{IN} . Turn off the regulator by grounding the control pin. See Figure B.

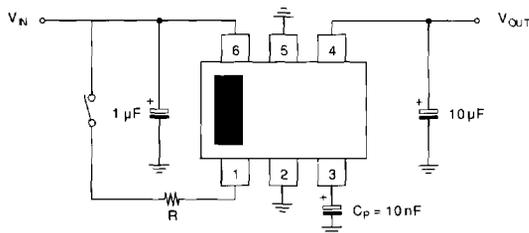


Figure B.

3.) HEAT DISSIPATION

Make the copper pattern as large as possible to provide good heat dissipation (pin 5 is the heatsink).
 $P_D = 400 \text{ mW}$ (When mounted as recommended)
 See Figure C.

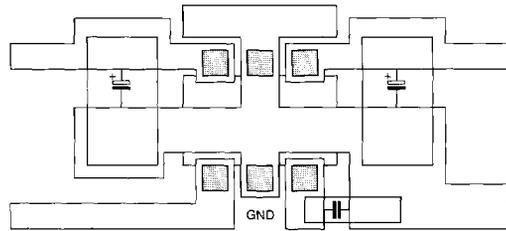


Figure C.

3

4.) BYPASS CAPACITOR

Connect the bypass capacitor as close as possible to the GND terminal of IC (Pin 5,2), otherwise oscillation may occur. Use a $3.3 \mu\text{F}$ tantalum capacitor, or $5.6 \mu\text{F}$ electrolytic to ensure stability. ($T_A = 25 \text{ C}$) For low temperatures, select a capacitor with low ESR at the desired temperature range. Use as large a capacitor as needed to meet transient, output impedance, and noise requirements. The noise bypass pin has high impedance, and it is sensitive to external noise if C_P is not used.

5. Handling Molded Resin Packages

All Plastic molded packages absorb some moisture from the air. If moisture absorption occurs prior to soldering the device into the printed circuit board, increased separation of the lead from the plastic molding may occur, degrading the moisture barrier characteristics of the device.

This property of plastic molding compounds should not be overlooked, particularly in the case of very small packages, where the plastic is very thin.

In order to preserve the original moisture barrier properties of the package, devices are stored and shipped in moisture proof bags, filled with dry air. The bags should not be opened or damaged prior to the actual use of the devices. If this is unavoidable, the devices should be stored in a low relative humidity environment (40 to 65%) or in an enclosed environment with desiccant.